

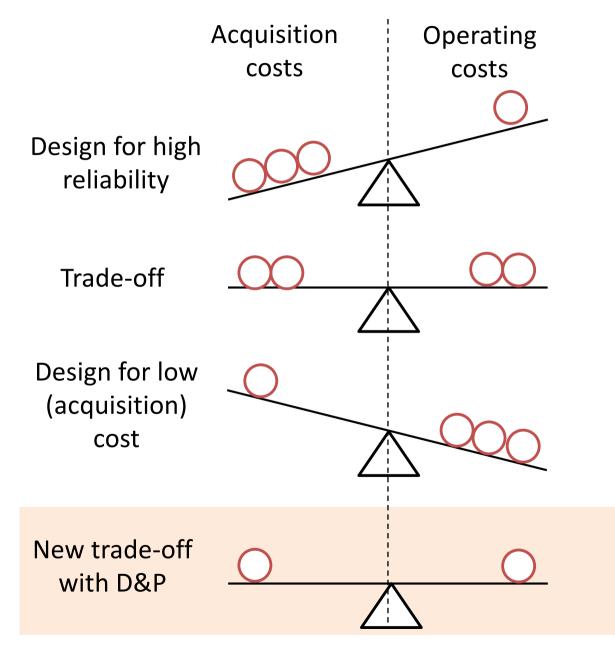
Robust On-line Junction Temperature Estimation of IGBT Power Modules based on Von during PWM Power Cycling

Prognostics Framework for Power Semiconductor IGBT Modules through Monitoring of the On-State Voltage

> IWIPP conference N. Degrenne, S. Mollov n.degrenne@fr.merce.mee.com April 2019 MFR19-ARC-0340



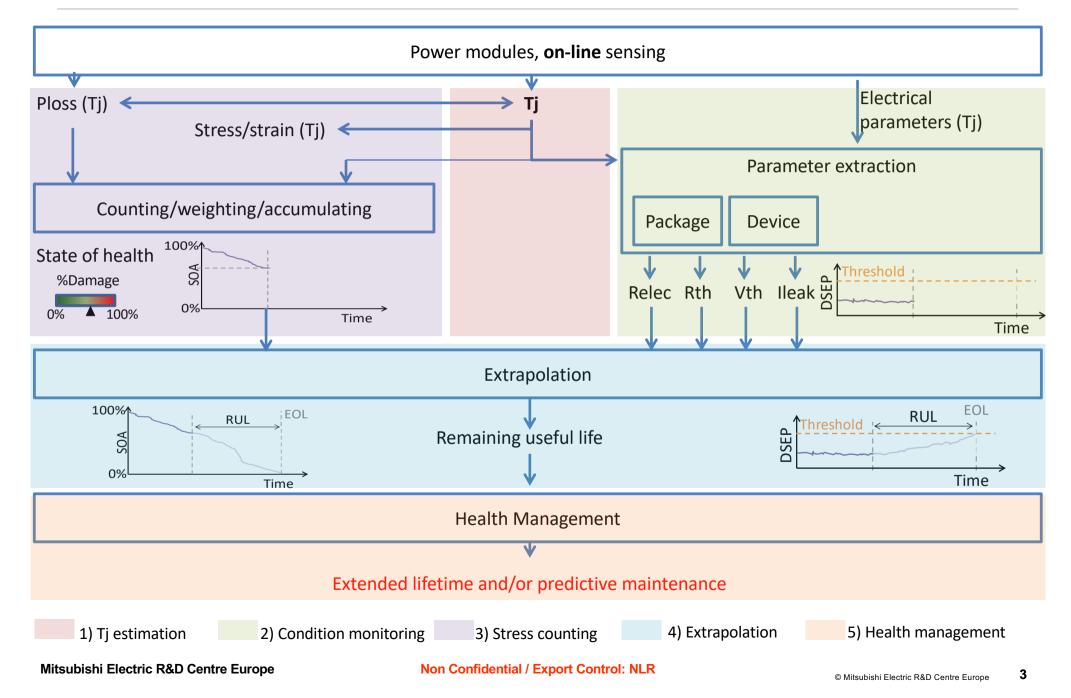
Introduction to Diagnostics & Prognostics (D&P)



- Design for reliability:
 - Trade-off: cost VS reliability
 - Reliability
 objectives (e.g.
 15years for
 Automotive)
- D&P breaks this relation and promises benefits in:
 - Availability
 - Security
 - Reliability
 - Design
 - Life-cycle cost



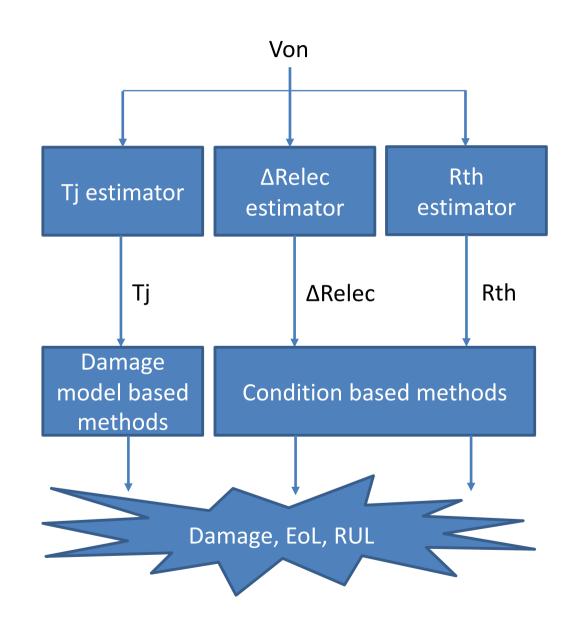
A review on D&P for power modules





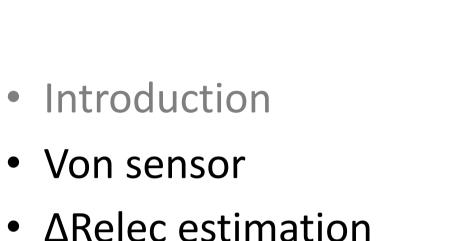
Von as a Temperature-SEP and Damage-SEP

- Pros of Von
 - Von is both a DSEP and a TSEP
 - ⇒Allows using a combination of methods
 - Von is applicable to IGBTs and Diodes
- Cons
 - Von is both a DSEP and a TSEP
 - \Rightarrow Discrimination needed
 - Von depends on current and presents variability from device to device
 ⇒Individual calibration needed

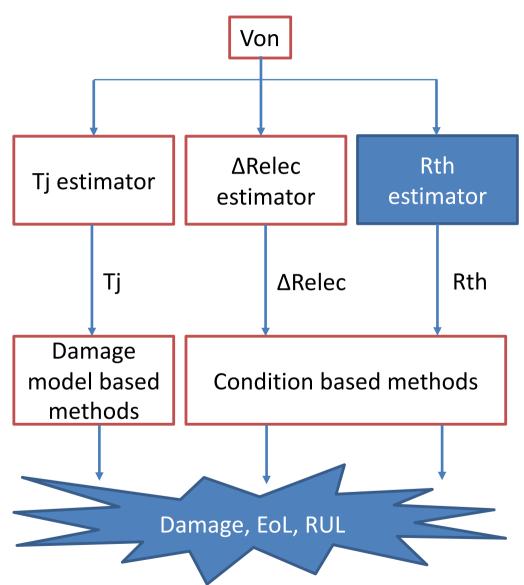




Outline



- Tj estimation
- Prognostic algorithm

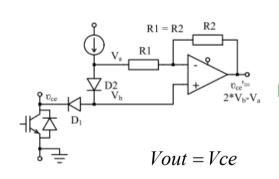




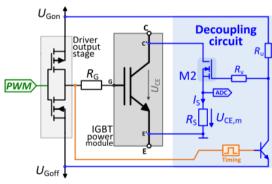
Von sensor: review

Number	Clamp method	Pros	Cons
1	De-sat style with 2 thermally-coupled HV diodes in series	Fast	 Fundamental issue with dispersion in diode thermal sensitivity
2	Active MOSFET clamp	Fast	 Requirement of (SiC) HV switches which are necessarily high-cost Complex control
3	Depletion mode MOSFET	Fast	 Requirement of HV depletion mode MOSFET which is not common
4	R-D clamp	Simple	Trade-off rapidity/ power consumption

1

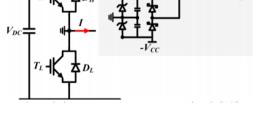


Example of desat style clamp (U. of Aalborg)



Example of active MOSFET clamp (U. of Bayreuth)

2



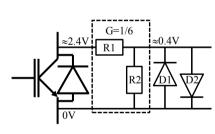
Example of desat style clamp

(U. of Aalborg)

3

Measurement circuit

Op-am



4

Example of R-D clamp (MERCE)



Von sensor: development & results

- Time-response: 8µs
- Precision: ±3,5mV
- Multiplexing:
 - related to Diff AOP, ADC and isolator (+ FPGA channel):
 - Multiple control strategies possible
- Cost: 8€ per switch

4.5

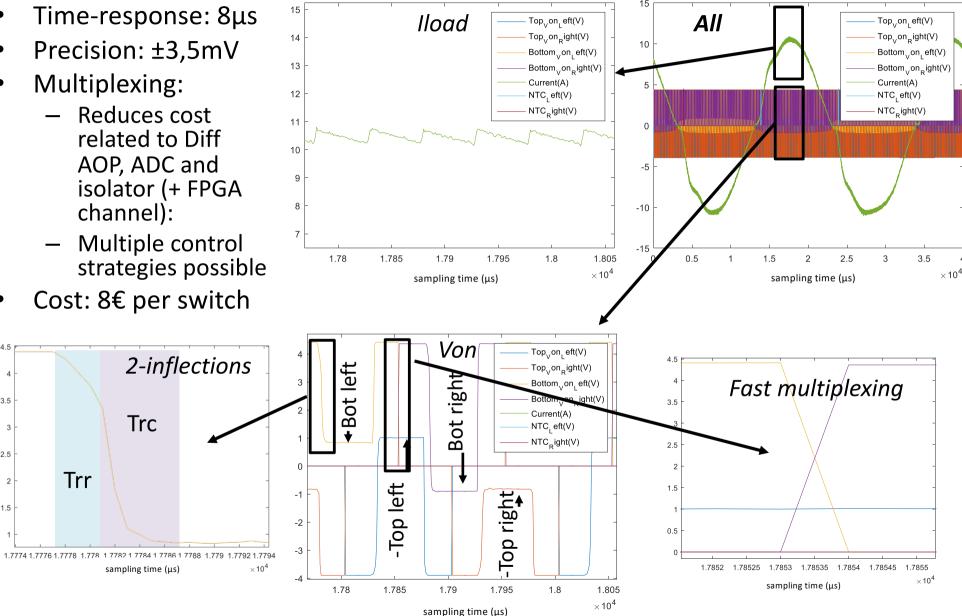
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3

2.5

2

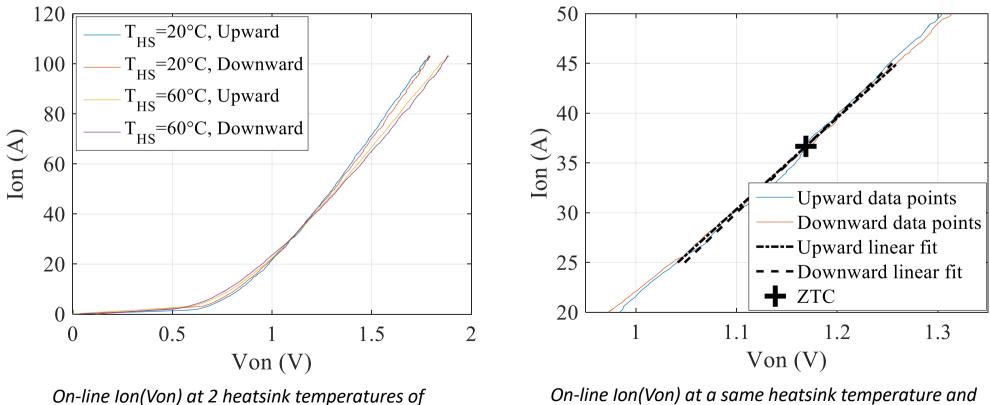
1.5





ΔRelec estimation: identification of ZTC current

- Motivation: more than 5A dispersion of ZTC current between identical devices/modules
- 2 strategies:
 - Acquisition at different heat-sink temperature
 - Acquisition at low modulating frequency



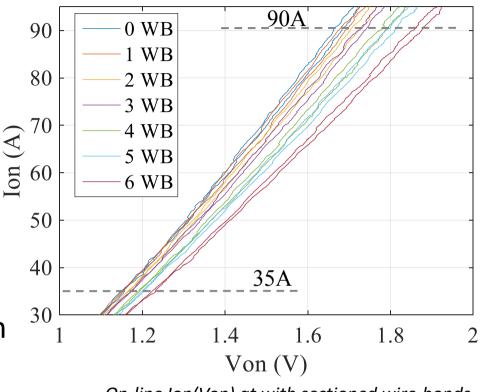
during increasing and decreasing current with linear fit

20°C and 60°C



ΔRelec estimation: sensitivity to WB lift-off

- Wire-bond sectioning experiment
- Sensitivity is proportional to current (2.6 ratio)
- \Rightarrow Specification for Von sensor:
 - High accuracy (mV level) for "early" prognostics
 - High precision (e.g. through additional filtering)



On-line Ion(Von) at with sectioned wire-bonds

	1% Von increase	Average Von jump	5% voltage increase
@ High current of 90A	18mV	33.2mV	90mV
@ ZTC of 35A	7mV	12.8mV	35mV

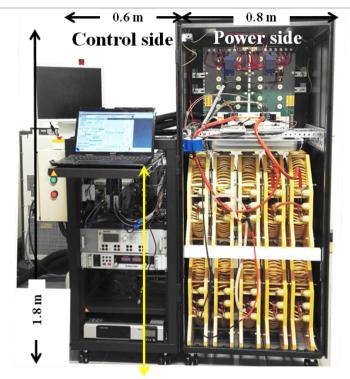


Tj estimation with Von: review

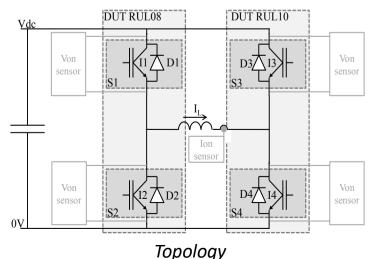
	Method 1: Von @ low	Method 2: Von @ any load	Method 3: Von @ low	Method 4: Von @ low	
	measurement current	current	load-current	load-current pulses	
Features	I I _{load} I _{meas}	I I _{load}	I	I I Iload	
	V Von + T X	$ \begin{array}{c} V \\ \downarrow \downarrow$	V Von T X	V Von T X	
Cost and calibration effort	$\star \diamond \diamond \diamond \diamond$	★★★☆☆ → ★★★★☆ (t	$t \Leftrightarrow$ (this paper demonstrates the use of a reduced calibration data)		
	 Von sensor Specific current source By-pass circuit 	 Von sensor Current sensor High calibration effort (calibration versus both temperature and current) 			
Intrusiveness and	**☆☆☆	****	***	★★★☆☆	
bandwidth	- Disconnects the power- device from power during measurement	 Does not interact with normal operation Can be performed at each switching period 	 Does not interact with normal operation Can be performed twice per modulating period of an inverter 	 Modifies the load current during 100µs to 200µs Each temperature estimation impacts load current and EMI 	
Accuracy	★★★☆ - The main issue is the cool- down during the delay before measurement	★☆☆☆ - Self-heating in calibration - High influence of the interconnect temperature - Low sensitivity for some current values close to ZTC - Uncertainty on current	★★★☆ - Uncertainty on current		
Robustness	****	★☆☆☆☆ - High sensitivity to wire- bond degradation	 ★★☆☆☆ → ★★★★☆ (this paper demonstrates a means to estimate and compensate for the wire-bond degradation) Medium sensitivity to wire-bond degradation 		
References	[4] [5] [6]	[7] [8] [9]	-	[11]	

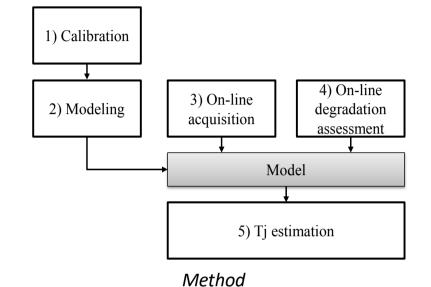


Tj estimation with Von at low load current pulse

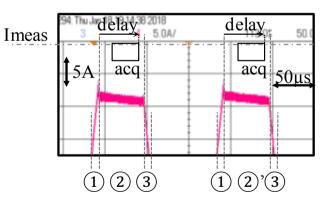








1) Calibration



2) Modeling

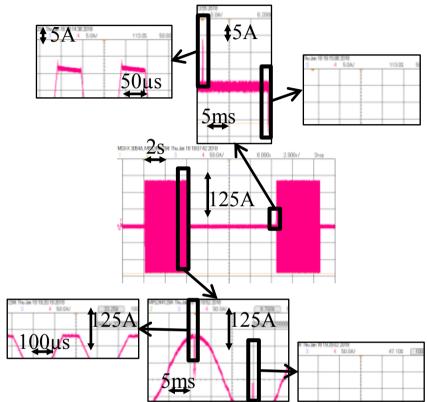
$$Von = (a \cdot Tj + b) \cdot Ion + (c \cdot Tj + d + e \cdot Tj^{2})$$

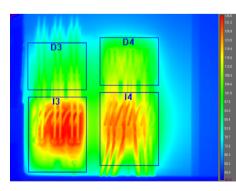
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Tj estimation with Von: results

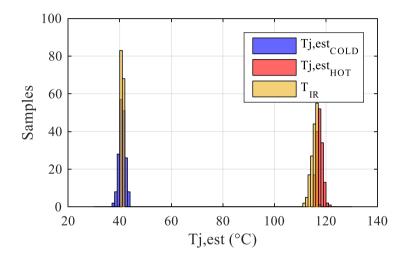
3) On-line acquisition



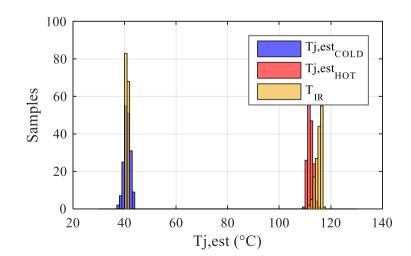


IR observation Mitsubishi Electric R&D Centre Europe

5) Tj estimation with full calibration dataset (20°C to 160°C)



5) Tj estimation with reduced calibration dataset (20°C to 70°C)





Tj estimation with Von: robustness

cold

hot

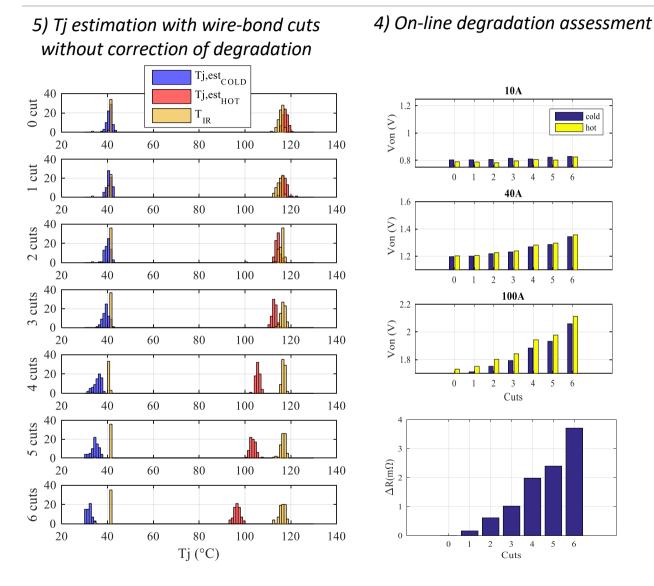
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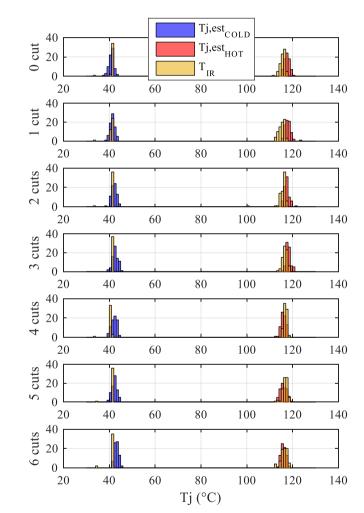
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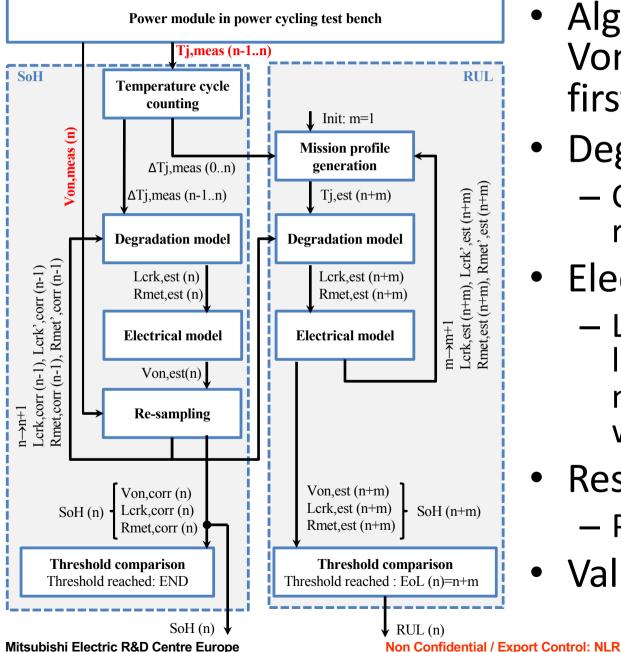


5) Tj estimation with wire-bond cuts with correction of degradation





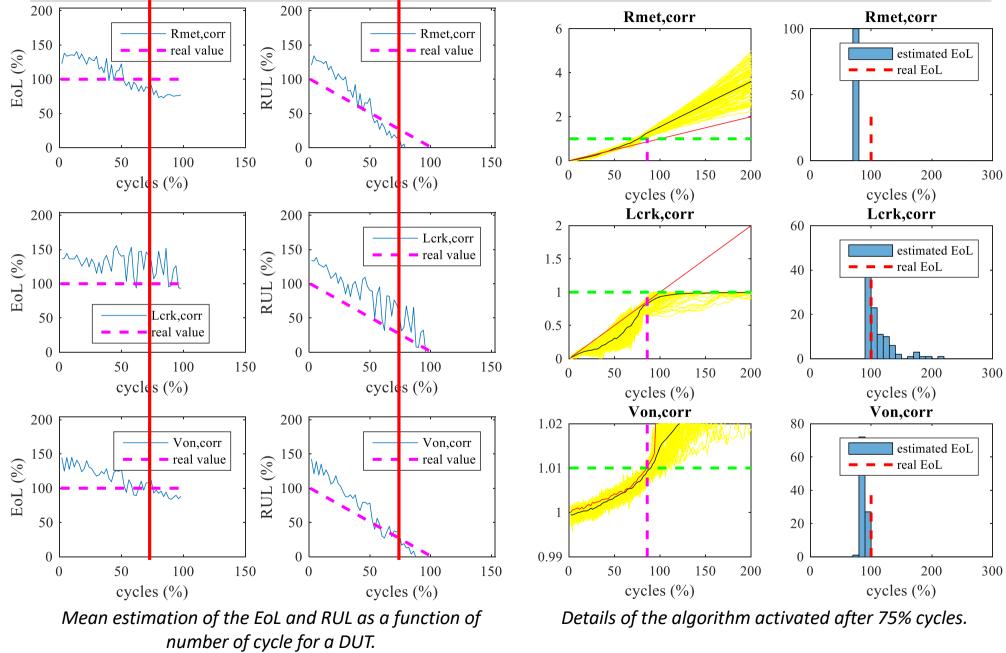
Prognostic algorithm: concept



- Algorithm based on Von evolution prior to first WB lift-off.
- Degradation model:
 Coffin-Manson + Min
 - Coffin-Manson + Miner rule
- Electrical model:
 - Linear increase of crack length and metallization, calibrated with training tests
- Resampling:
 Particle filter
- Validation: DC PC data.



Prognostic algorithm: results



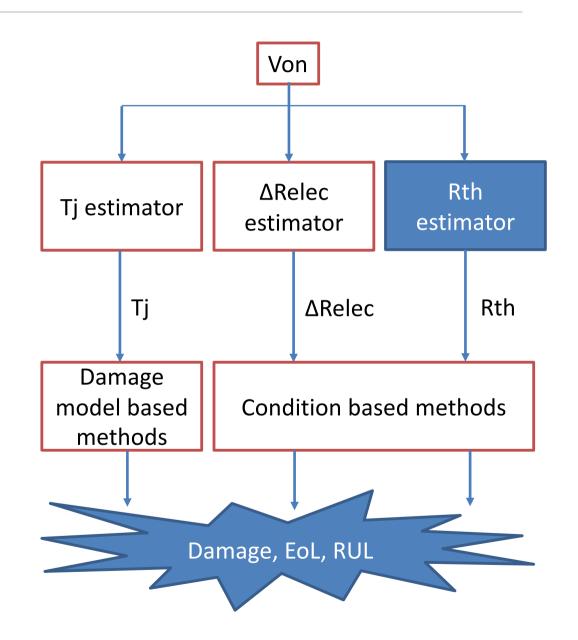
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Conclusion/Outline



- Von sensor
- ΔRelec estimation
- Tj estimation
- Prognostic algorithm



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Thank you for your attention

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